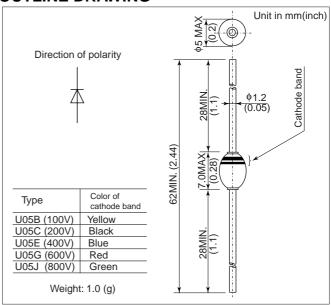
U05

FEATURES

- For general purpose.
- Diffused-junction. Glass passivated and encapsulated.

OUTLINE DRAWING



ABSOLUTE MAXIMUM RATINGS

| Item | Ту | ре | U05B | U05C | U05E | U05G | U05J | | |
|---------------------------------------|--------------------|------------------|---|------|------|------|------|--|--|
| Repetitive Peak Reverse Voltage | V_{RRM} | V | 100 | 200 | 400 | 600 | 800 | | |
| Non-Repetitive Peak Reverse Voltage | V _{RSM} | V | 200 | 300 | 500 | 800 | 1000 | | |
| Average Forward Current | I _{F(AV)} | А | 2.5 (Single-phase half sine wave 180° conduction TL = 90°C, Lead length = 10mm | | | | | | |
| Surge(Non-Repetitive) Forward Current | I _{FSM} | А | 100 (Without PIV, 10ms conduction, Tj = 175°C start) | | | | | | |
| I²t Limit Value | l ² t | A ² s | 40 (Time = 2 ~ 10ms, I = RMS value) | | | | | | |
| Operating Junction Temperature | T _j | °C | -65 ~ +175 | | | | | | |
| Storage Temperature | T_{stg} | °C | -65 ~ +200 | | | | | | |

Notes (1) Lead Mounting: Lead Temperature 300°C max. to 3.2mm from body for 5sec. Max..

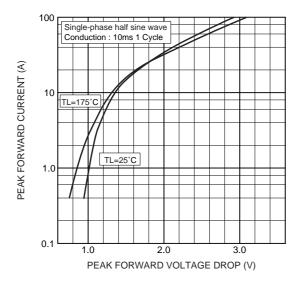
(2) Mechanical Strength: Bending 90°×2 cycles or 180°×1 cycle, Tensile 3kg, Twist 90°×1 cycle.

CHARACTERISTICS(T. =25°C)

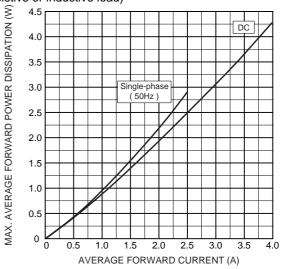
| Item | Symbols | Units | Min. | Тур. | Max. | Test Conditions | |
|--------------------------------|----------------------|-------|------|------|------|---|------------------------|
| Peak Reverse Current | | μΑ | _ | 1.5 | 60 | B,C class | Poted V |
| | IRRM | | | 0.6 | 10 | E,G,J class | Rated V _{RRM} |
| Peak Forward Voltage | V_{FM} | V | _ | _ | 1.1 | I _{FM} =2.5Ap, Single-phase half sine wave 1 cycle | |
| Reverse Recovery Time | trr | μs | _ | 3.0 | _ | I _F =2mA, V _R =-15V | |
| Steady State Thermal Impedance | R _{th(j-a)} | °C/W | _ | _ | 60 | Lead length = 10 mm | |
| | $R_{th(j-l)}$ | C/VV | | | 30 | | |

U05

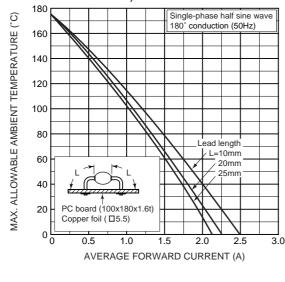
Forward characteristic



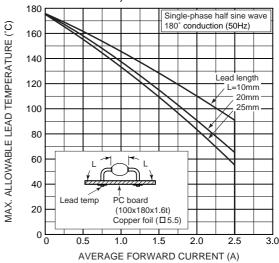
Max. average forward power dissipation (Resistive or inductive load)



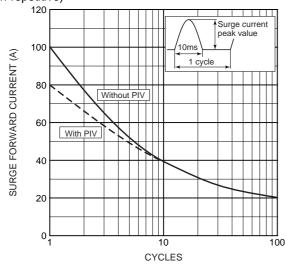
Max. allowable ambient temperature (Resistive or Inductive Load)



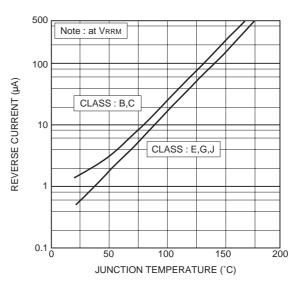
Max. allowable lead temperature (Resistive or inductive load)



Surge forward current characteristic (Non-repetitive)



Typ. reverse current vs. junction temperature

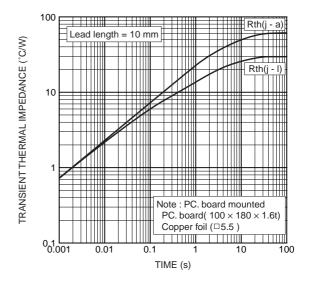


U05

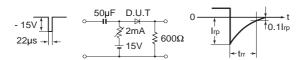
Steady state thermal impedance

Ambient temp. measured point STEADY STATE THERMAL IMPEDANCE (°C/W) Lead temp. measured poin 100 (φ0.5 thermocouple) Copper foil (□5.5) PC board (100×180×1.6t) 80 Rth(j - a) 60 Rth(j - I) 40 20 ٥ 10 25 30 5 15 LEAD LENGTH (mm)

Transient thermal impedance



Reverse recovery time(trr) test circuit



HITACHI POWER SEMICONDUCTORS

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